

Abstract

A thermal interface for facilitating heat transfer from an electronic component to a heat sink. According to a preferred embodiment, the thermal interface comprises a first planar substrate that defines a first continuous peripheral edge, at least a portion of which extends beyond the interface mating surface between the electronic component and heat sink. Formed upon opposed sides of the substrate are layers of thermally conductive compositions, which preferably comprise certain novel graphitic allotrope compounds. The thermal interface further includes an adhesive deposited upon such portion of the peripheral edge extending beyond the mating surface between the electronic component and heat sink such that the thermal interface may be adhesively secured into position without forming an additional layer at the mating juncture between the electronic component and the heat sink.